

1

2 가

3 2

4 가 , 가

5

** **

10: 2:

3: 50:

52: 53:

530: 101:

21:

가

, TCP(Tape Carrier Package), (Surface Mount Technology, SMT)
 DIP(Dual In-line Package), PGA(Pin Grid Array), CLCC(Ceramic Leaded Chip Carrier), BGA(Ball Grid Array), QFP(Quad Flat Package), PLCC(Plastic Leaded Chip Carrier)

가

1

(2) 가 (21) (1) (11) (2) (3) ,
 가 (2) (1)가
 (21) (11) (3)가 가
 (1) (5) (5) (5: Fiducial Mark)

(5) 1 , 1 2 (5) , CCD

(12) (5) (1)

3)가 (1) (12)가 , (12) (11) (

(12)가 (1) (12) 가 (11) (11)가 (11)

(3) 가, (12) (11)가 (11)

가 , 가 , 가

2 가 , 3

2 3 , (10) (13) , (13) (12)

(11) (10) (2) (2) (11)가
(13) (3)가 (12)

(11) (2) 가 (21) (3)
(3) Au , Au, Cu Al

(2) (50) (11) (11) 1 4 (50)가

(50) , □ , (53) , □ , (52)
(52) (53) ()

4 (12)가 (50) (12)가
(50')

4 (12)가 (12)가 가 ,
() CCD 가

(10) (12)가 h Y (50') 4
(12)

(101) h (12) (3)

(10) (50) (10)가 (10)

(50) (53) , (53) (530) 가
(10)가 (53)

(530) (12)

(50) (12) (h)

(101)

(50) (53) (10)가 (12)
가 1 가 (530)
(50) 2 2가

5

(53) , (52)

(52) (53) 가 (530) 가 (12)

가

가 . ,

(57)

1.

, 가 ,

가 ,

가

2.

1 ,

3.

1 ,

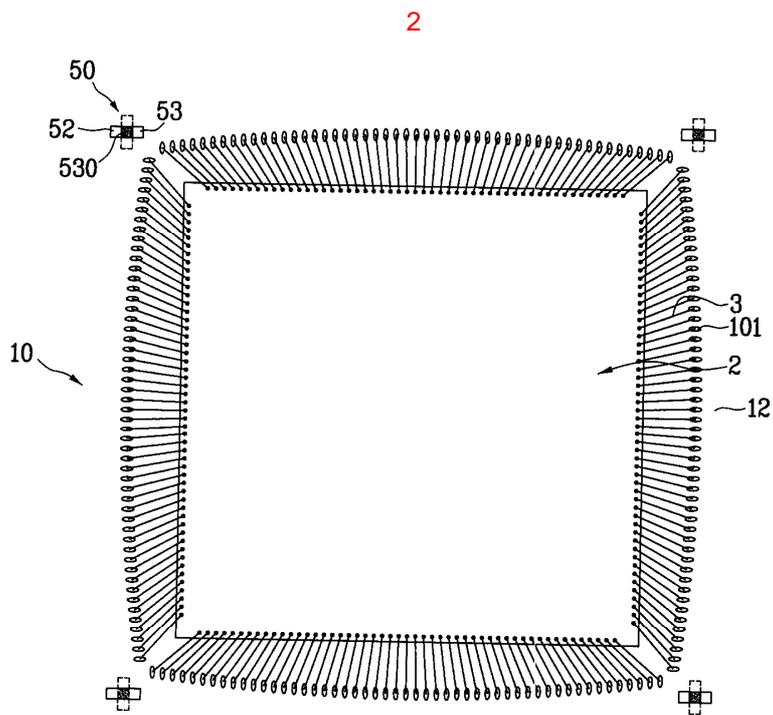
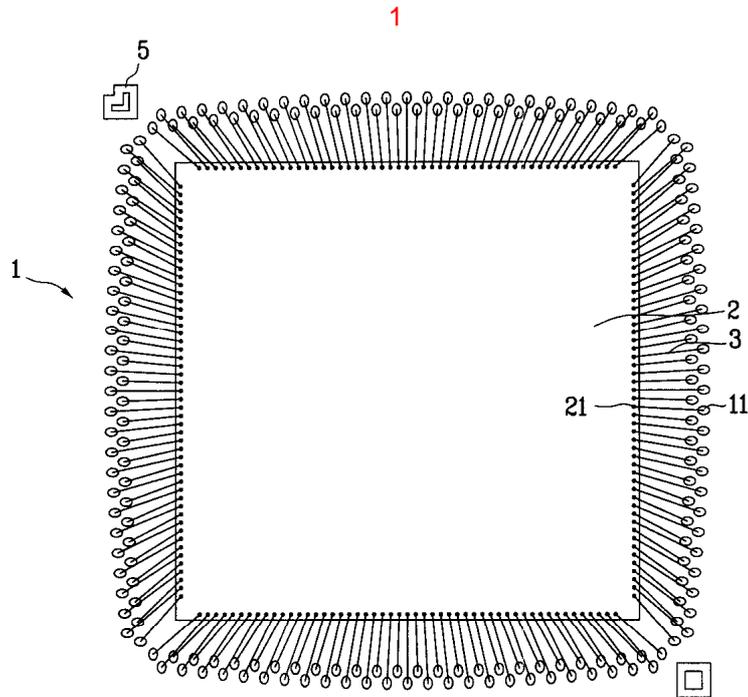
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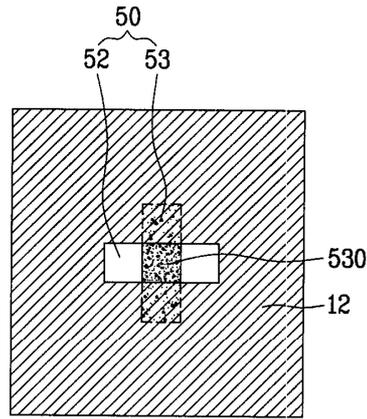
4.

1 ,

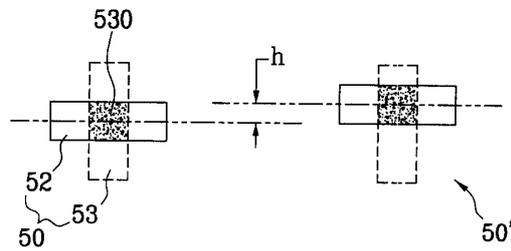
1 4 ,



3



4



5

